

Title (en)
METHOD FOR THE PRODUCTION OF AN ELECTRICALLY-CONDUCTING FRAME, METHOD FOR PRODUCTION OF A SURFACE MOUNTING SEMICONDUCTOR COMPONENT AND CONDUCTOR FRAME STRIPS

Title (de)
VERFAHREN ZUM HERSTELLEN EINES ELEKTRISCHEN LEITERRAHMENS, VERFAHREN ZUM HERSTELLEN EINES OBERFLÄCHENMONTIERBAREN HALBLEITERBAUELEMENTS UND LEITERRAHMENSTREIFEN

Title (fr)
PROCEDE POUR REALISER UN CADRE ELECTRIQUEMENT CONDUCTEUR ET PROCEDE POUR REALISER UN COMPOSANT SEMI-CONDUCTEUR QUI PEUT ETRE MONTE EN SURFACE, ET STRIE DE CADRE CONDUCTEUR

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Abstract (en)
[origin: WO2004015769A1] The invention relates to a method for the production of an electrically conducting frame (10), in particular for a light diode component, with at least one first (2) and one second electrical connection conductor (3). The method comprises the following steps: a) production of a layer composite made from an electrically-insulating support layer (101) and an electrically-conducting connection conductor layer (102), b) structuring the support layer (101) such that at least one contact window (7) facing the connection conductor layer (102) is generated therein, c) structuring the connection conductor layer (102) such that the first (2) and the second electrical connection conductor (3) are generated, of which at least one may be electrically connected through the contacting window (7). The invention further relates to a conductor frame strip with a connection conductor layer and connector support layer, upon which a field with a number of component regions is embodied, whereby the connection conductor layer is at least partly removed along separation lines between two adjacent component regions.

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